

#### ABSTRACT

A method of making a microelectronic assembly includes providing a dielectric layer including a first major face comprising a first adhesive, a second major face comprising a second adhesive, and a protective liner over the second adhesive, juxtaposing a plurality of microelectronic elements with the first major face of dielectric layer, and assembling the microelectronic elements with the dielectric layer by abutting the microelectronic elements against the first adhesive of the dielectric layer. The method also includes at least partially severing the dielectric layer while maintaining the protective liner as a single piece of material so as to form a plurality of individual microelectronic units overlying the protective liner, whereby each of the individual microelectronic units includes at least one of the microelectronic elements attached to an at least partially severed portion of the dielectric layer.

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